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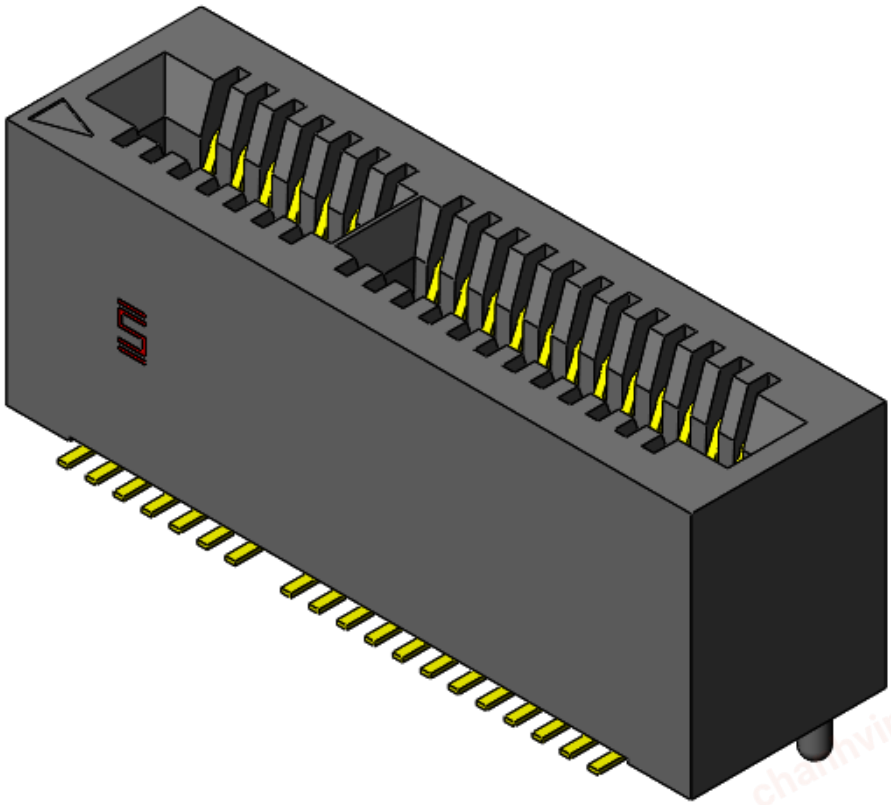
Series: MEC1 1.00 mm (.0394”) Mini Edge Card Socket

MEC1 Series – Socket, Vertical Orientation



Other configurations available for:

Right Angle Application, Edge Mount Application

See www.samtec.com for more information.

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1.0 SCOPE

1.1 This specification covers performance, testing and quality requirements for Samtec's MEC1 Series 1.00 mm (.0394") Mini Edge Card Socket. All information contained in this specification is for a Vertical 1.57 mm (.062") Edge Card configuration unless otherwise noted.

2.0 DETAILED INFORMATION

2.1 Product prints, footprints, catalog pages, test reports and other specific, detailed information can be found at http://www.samtec.com/?MEC1.

3.0 TESTING

3.1 Current Rating: 2.2 A (2 Pins powered)

3.2 Voltage Rating: 250 VAC

3.3 Operating Temperature Range: -55°C to +125°C

3.4 Electrical:

ITEM	TEST CONDITION	REQUIREMENT	STATUS
Withstanding Voltage	EIA-364-20 (No Flashover, Sparkover, or Breakdown)	750 VAC	Pass
Insulation Resistance	EIA-364-21 (1000 MΩ minimum)	5,000 MΩ	Pass
Contact Resistance (LLCR)	EIA-364-23	Δ 15 mΩ maximum (Samtec defined)/ No damage	Pass

3.5 Mechanical:

ITEM	TEST CONDITION	REQUIREMENT	STATUS
Durability	EIA-364-09C	500 cycles	Pass
Random Vibration	EIA-364-28 Condition V, Letter B 7.56 G 'RMS', 50 to 2000 Hz, 2 hours per axis, 3 axis total , PSD 0.04	Visual Inspection: No Damage LLCR: Δ 15 mΩ maximum	Pass
Mechanical Shock	EIA-364-27 100 G, 6 milliseconds, sawtooth wave, 11.3 fps, 3 shocks/direction, 3 axis (18 total shocks)	Visual Inspection: No Damage LLCR: Δ 15 mΩ maximum	Pass
Normal Force	EIA-364-04	30 grams minimum for Gold interface	Pass

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3.6 Environmental:

ITEM	TEST CONDITION	REQUIREMENT	STATUS
Thermal Shock	EIA-364-32 Thermal Cycles: 100 (30 minute dwell) Hot Temp: 85°C Cold Temp: -55°C Hot/Cold Transition: Immediate	Visual Inspection: No Damage LLCR: Δ 15 mΩ DWV: 750 VAC IR: >10,000 MΩ	Pass
Thermal Aging (Temp Life)	EIA-364-17 Test Condition 4 @ 105°C Condition B for 250 hours	Visual Inspection: No Damage LLCR: Δ 15 mΩ DWV: 750 VAC IR: >10,000 MΩ	Pass
Cyclic Humidity	EIA-364-31 Test Temp: 25°C to 65°C Relative Humidity: 90 to 95% Test Duration: 240 hours	Visual Inspection: No Damage LLCR: Δ 15 mΩ DWV: 750 VAC IR: >10,000 MΩ	Pass
Gas Tight	EIA-364-36 Gas Exposure: Nitric Acid Vapor Duration: 60 min. Drying Temp.: 50°C +/- 3°C Measurements: Within 1 hour of Exposure	LLCR: Δ 15 mΩ	Pass

4.0 MATED SYSTEM

4.1 Mated Views

Mated view information can be found at link below:

http://suddendocs.samtec.com/prints/mec1%20mated%20document-mkt.pdf

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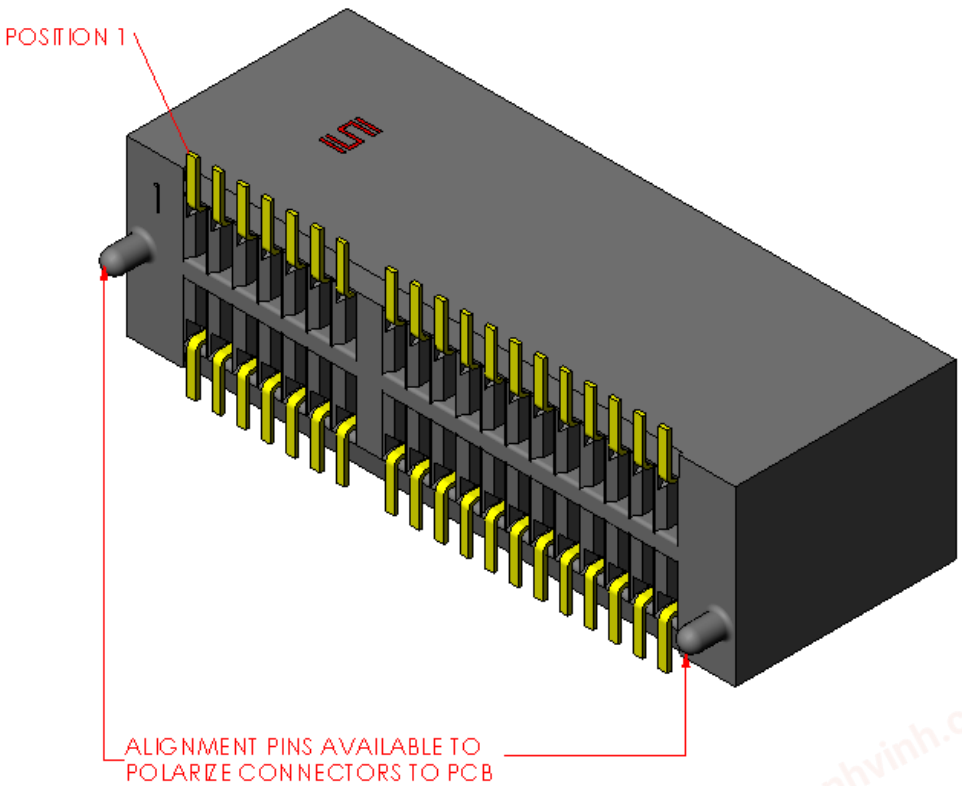
5.0 POLARIZING FEATURES



6.0 HIGH SPEED PERFORMANCE

6.1 Based on a 3 dB insertion loss
6.2 System Impedance: 50 ohm for single-ended and 100 ohm for differential pair

MEC1	
Single-Ended Signaling	**Differential Pair Signaling**
5.5 GHz/11 Gbps	6.5 GHz/13 Gbps

MEC1-RA			
Inner Row Single-Ended Signaling	**Inner Row Differential Pair Signaling**	**Outer Row Single-Ended Signaling**	**Outer Row Differential Pair Signaling**
4.5 GHz/9 Gbps	5.5 GHz/11 Gbps	3.0 GHz/6 Gbps	4.0 GHz/8 Gbps

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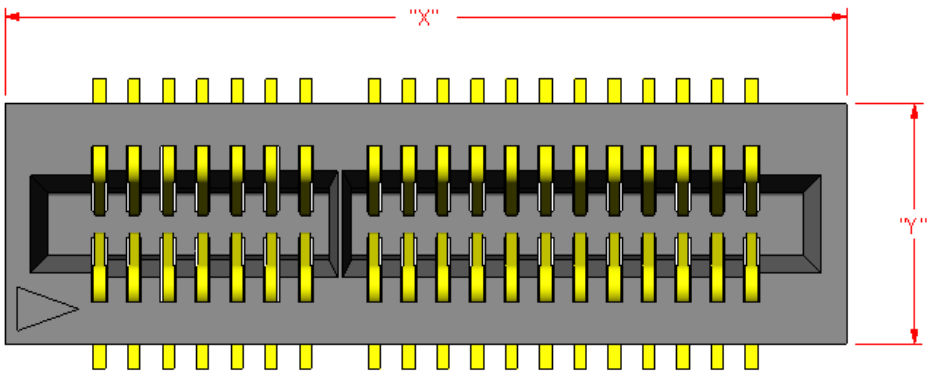
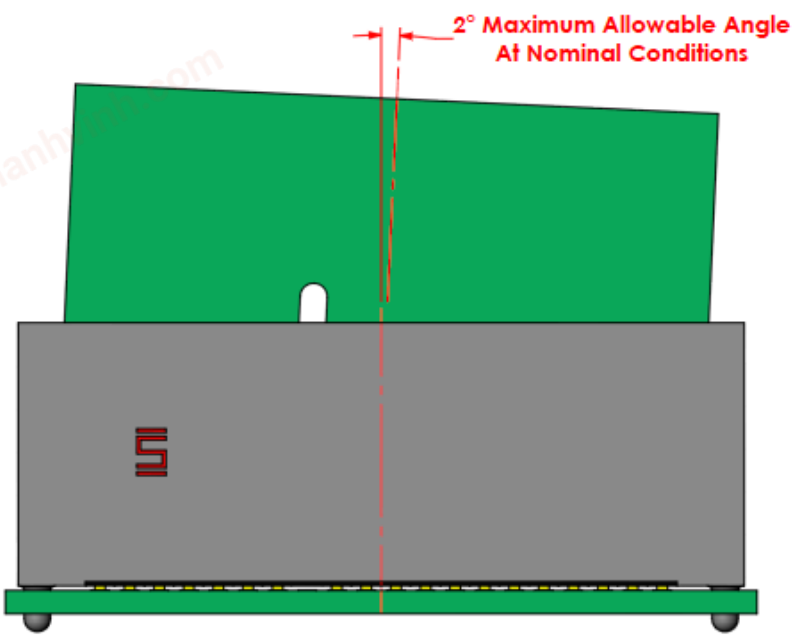
7.0 PROCESSING RECOMMENDATIONS

7.1 Mating Alignment Requirements:

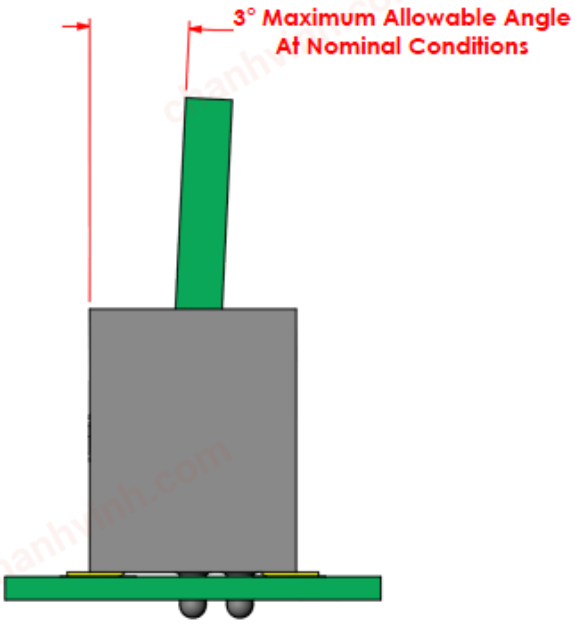
7.1.1 The parts can be rigidly misaligned by no more than .12 mm (.005”) in the X- and .13 mm (.005”) in the Y-direction to ensure a good mate.



7.2 Mating Angle Requirements:



7.2.1



7.2.2

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7.3 Multiple Connector Applications: Not recommended for applications in which multiple connectors are mated to a single daughtercard. For more information, please contact IPG@Samtec.com.

7.4 Due to variances in equipment, solder pastes and applications (board design, component density, etc.), Samtec does not specify a recommended reflow profile for our connectors. The processing parameters provided by the solder paste manufacturer should be employed and can usually be found on their website.

All of Samtec's surface mount components are lead free reflow compatible and compliant with the profile parameters detailed in IPC/JEDEC J-STD-020 which requires that components be capable of withstanding a peak temperature of 260°C as well as 30 seconds above 255°C.

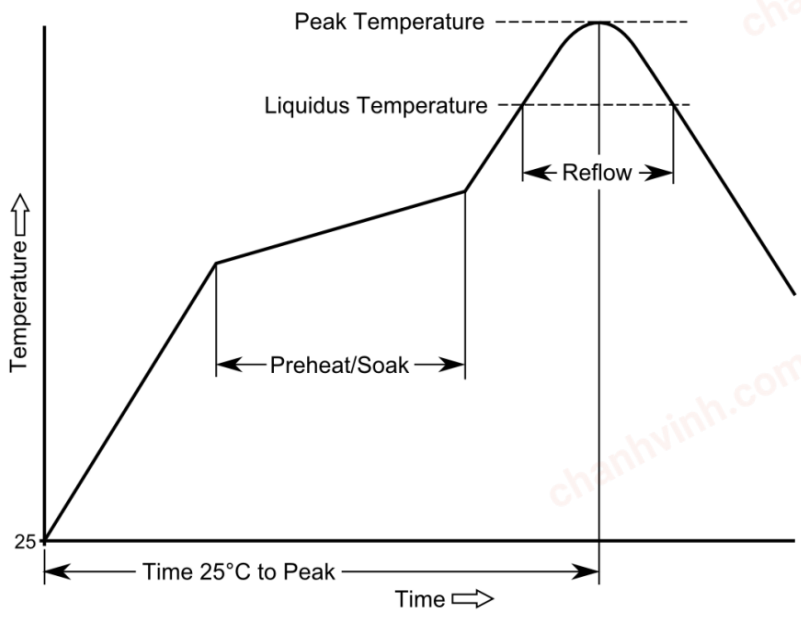
Samtec Recommended Temperature Profile Ranges (SMT)

Sn-Pb Eutectic Assembly

Preheat/Soak (100°C-150°C)	Max Ramp Up Rate	Reflow Time (above 183°C)	Peak Temp	Time within 5°C of 235°C	Max Ramp Down Rate	Time 25°C to Peak Temp
60-120 sec.	3°C/s max.	40-150 sec.	235°C	20 sec. max.	6°C/s max.	6 min. max.

Pb-Free Assembly

Preheat/Soak (150°C-200°C)	Max Ramp Up Rate	Reflow Time (above 217°C)	Peak Temp	Time within 5°C of 260°C	Max Ramp Down Rate	Time 25°C to Peak Temp
60-120 sec.	3°C/s max.	40-150 sec.	260°C	30 sec. max.	6°C/s max.	8 min. max.



7.4.1

These guidelines should not be considered design requirements for all applications.
Samtec recommends testing interconnects on your boards in your process to guarantee optimum results.

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7.5 Maximum Reflow Passes: The parts can withstand three reflow passes at a maximum component temperature of 260°C.

7.6 Stencil Thickness: The stencil thickness is .006" (.15 mm).

7.7 Placement: Machine placement of the parts is strongly recommended.
Note: If the Locking Clip option (-LC) is used, manual placement will be required if the force needed to fully seat the connector exceeds the limit of the machine placement equipment. For more information, please visit the Processing page on our website or contact Samtec's Interconnect Processing Group at IPG@samtec.com.

7.8 Reflow Environment: Samtec recommends the use of a low level oxygen environment (typically achieved through Nitrogen gas infusion) in the reflow process to improve solderability.

7.9 Cleaning: Samtec, Inc. has verified that our connectors may be cleaned in accordance with the solvents and conditions designated in the EIA-364-11 standard.

7.10 Inverted Reflow: For applications of the Right Angle (-RA) option requiring inverted reflow soldering, use of an epoxy adhesive is recommended. For more information on the use of epoxy adhesives, please visit the Processing page on our website or contact Samtec's Interconnect Processing Group at IPG@samtec.com.

8.0 ADDITIONAL RESOURCES

8.1 For additional mechanical testing or product information, contact our Customer Engineering Support Group at **CES@samtec.com**

8.2 For additional information on high speed performance testing, contact our Signal Integrity Group at **SIG@samtec.com**

8.3 For additional processing information, contact our Interconnect Processing Group at **IPG@samtec.com**.

8.4 For RoHS, REACH or other environmental compliance information, contact our Product Environmental Compliance Group at **PEC@samtec.com**

USE OF PRODUCT SPECIFICATION SHEET

This Product Specification Sheet ("PSS") is a brief summary of information related to the Product identified. As a summary, it should only be used for the limited purpose of considering the purchase/use of Product. For specific, detailed information, including but not limited to testing and Product footprint, refer to Section 2.0 of this document and the links there provided to test reports and prints. This PSS is the property of Samtec, Inc. ("Samtec") and contains proprietary information of Samtec, our various licensors, or both. Samtec does not grant express or implied rights or license under any patent, copyright, trademark or other proprietary rights and the use of the PSS for building, reverse engineering or replication is strictly prohibited. By using the PSS, the user agrees to not infringe, directly or indirectly, upon any intellectual property rights of Samtec and acknowledges that Samtec, our various licensors, or both own all intellectual property therein. The PSS is presented "AS IS". While Samtec makes every effort to present excellent information, the PSS is only provided as a guideline and does not, therefore, warrant it is without error or defect or that the PSS contains all necessary and/or relevant information about the Product. The user agrees that all access and use of the PSS is at its own risk. **NO WARRANTIES EXPRESSED OR IMPLIED, INCLUDING ANY WARRANTY OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR OF ANY KIND WHATSOEVER ARE PROVIDED.**